



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-02-12
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32MP257AAL3	E2K3*505XXXY	A	9991	2025-02-12
Amount	Unit of measure	Unit type	ST ECOPACK grade	
200	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
NAC	Not Applicable	NAC	SACN305	
Package designator	Package size	Number of instances	Shape	
WLCSP	10x10	361	Bulk solder	
Comment	Package : B09U FC VFBGA 10X10 361B P0.5 DM00517380			

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-7th November 2024				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	E2K3*505XXX1		200.1020		5000000.0	1000000.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	10.000	mg	supplier	die	Silicon(Si)	7440-21-3		9.329	mg	932860	46619.21651
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.005	mg	500	24.98725238
				supplier	metallisation	Arsenic(As)	7440-38-2		0.000	mg	4	0.199898019
				supplier	metallisation	Copper(Cu)	7440-50-8		0.498	mg	49763	2486.88128
				supplier	metallisation	Cobalt(Co)	7440-48-4		0.000	mg	29	1.449260638
				supplier	metallisation	Silver(Ag)	7440-22-4		0.002	mg	196	9.795002932
				supplier	metallisation	Tantalum(Ta)	7440-25-7		0.005	mg	500	24.98725238
				supplier	metallisation	Tin(Sn)	7440-31-5		0.107	mg	10667	533.0780422
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.001	mg	108	5.397246514
				supplier	metallisation	Tungsten(W)	7440-33-7		0.006	mg	550	27.48597762
				supplier	Passivation	Silicon Nitride (SiN)	12033-89-5		0.014	mg	1399	69.91433215
				supplier	passivation	Silicon Oxide	7631-86-9		0.034	mg	3424	171.1127043
				Substrate (A32502)	Copper & Resin	50.570	mg	supplier	Solder Mask	Plastics PAK	Proprietary	
supplier	Solder Mask	Barium sulphate	7727-43-7						0.563	mg	11136	2814.311915
supplier	Solder Mask	Plastic EP	Proprietary						0.362	mg	7159	1809.23662
supplier	Solder Mask	Silicon dioxide	7631-86-9						0.287	mg	5682	1435.966262
supplier	Solder Mask	Additives, not to declare	Proprietary						0.129	mg	2557	646.2100903
supplier	Solder Mask	Talc	14807-96-6						0.086	mg	1704	430.6382456
supplier	Solder Mask	Pigment portion, not to declare	Proprietary						0.017	mg	341	86.17819351
supplier	Solder Mask	Inorganic Ingredient, not to declare	Proprietary						0.017	mg	341	86.17819351
supplier	PP	Thermosetting resin (including filler)	Proprietary						10.260	mg	202885	51273.49792
supplier	PP	Glass Cloth	65997-17-3						6.840	mg	135258	34182.66891
supplier	Cu foil	Copper	7440-50-8						3.411	mg	67450	17046.09722
supplier	Cu Plating	Copper	7440-50-8						27.186	mg	537591	135861.0593
Underfill (UA26)	Encapsulation Glue	2.000	mg					supplier	Underfill	p-(2,3-epoxypropoxy)-N, N-bis(2,3-epoxypropyl)am	5026-74-4	
				supplier	Underfill	Bisphenol F type liquid epoxy resin	9003-36-5		0.200	mg	100000	999.4900951
				supplier	Underfill	Bisphenol A type liquid epoxy resin	25068-38-6		0.060	mg	30000	299.8470285
				supplier	Underfill	Amine type hardener	Proprietary		0.150	mg	75000	749.6175714
				supplier	Underfill	Carbon black	1333-86-4		0.010	mg	5000	49.97450476
				supplier	Underfill	Silicon dioxide	60676-86-0		1.300	mg	650000	6496.685618
				supplier	Underfill	Additives	Proprietary		0.080	mg	40000	399.7960381
Encapsulation (EME-G760-SW)	Molding Compound	99.785	mg	supplier	Molding compound	2,2'-((3,3',5,5'-Tetramethyl-(1,1'-biphenyl)-4,4'-diylidene)bis(4-methylphenol))	85954-11-6		7.983	mg	80000	39893.63566
				supplier	Molding compound	Phenol Resin A	9003-35-4		3.991	mg	40000	19946.81783
				supplier	Molding compound	Phenol Resin B	Proprietary		3.991	mg	40000	19946.81783
				supplier	Molding compound	Silica(Amorphous) A	60676-86-0		59.871	mg	600000	299202.2675
				supplier	Molding compound	Silica(Amorphous) B	7631-86-9		19.957	mg	200000	99734.08916
				supplier	Molding compound	Metal Hydroxide	Proprietary		2.994	mg	30000	14960.11337
				supplier	Molding compound	Carbon Black	1333-86-4		0.998	mg	10000	4986.704458
Solder balls (SACN305)	Other inorganic materials	37.747	mg	supplier	Solder Ball	Tin	7440-31-5		36.350	mg	963000	181658.561
				supplier	Solder Ball	Silver	7440-22-4		1.246	mg	33000	6225.059722
				supplier	Solder Ball	Copper	7440-50-8		0.132	mg	3500	660.2336069
				supplier	Solder Ball	Nickel	7440-02-0		0.019	mg	500	94.3190867